

SY58020U

6 GHz, 1:4 CML Fanout Buffer/Translator with Internal I/O Termination

Features

- · Precision 1:4, 400 mV CML Fanout Buffer
- Guaranteed AC Performance Over Temperature/Voltage:
- > 6 GHz f_{MAX} Clock
- < 60 ps t_r / t_f Times
- < 250 ps t_{pd}
- < 15 ps Max. Skew
- · Low-jitter Performance:
- 27 fs_{RMS} Typical Additive Phase Jitter
- · Accepts an Input Signal as low as 100 mV
- Unique Patented Input Termination and VT Pin Accepts DC-coupled and AC-coupled Differential Inputs: LVPECL, LVDS, and CML
- 50Ω Source Terminated CML Outputs
- Power Supply 2.5V ±5% and 3.3V ±10%
- Industrial Temperature Range: –40°C to +85°C
- Available in 3 mm × 3 mm 16-lead VQFN Package

Applications

- · All SONET and All GigE Clock Distribution
- · Fibre Channel Clock and Data Distribution
- · Backplane Distribution
- Data Distribution: OC-48, OC-48+FEC, XAUI
- High-end, Low Skew, Multiprocessor Synchronous Clock Distribution

General Description

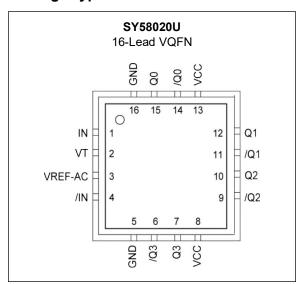
The SY58020U is a 2.5V/3.3V precision, high-speed, fully differential 1:4 CML fanout buffer. Optimized to provide four identical output copies with less than 15 ps of skew and 27 fs_{RMS} of typical additive phase jitter, the SY58020U can process clock signals as fast as 6 GHz.

The differential input includes Microchip's unique, 3-pin input termination architecture that interfaces to differential LVPECL, LVDS, and CML signals (AC- or DC-coupled) as small as 100 mV without any level-shifting or termination resistor networks in the signal path.

For AC-coupled input interface applications, an on-board output reference voltage (V_{REF-AC}) is provided to bias the VT pin. The outputs are optimized to drive 400 mV typical swing into 50 Ω loads, with extremely fast rise/fall times guaranteed to be less than 60 ps.

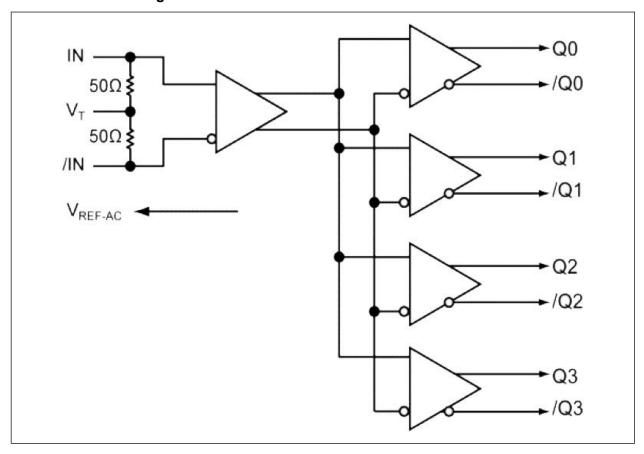
The SY58020U operates from a 2.5V $\pm 5\%$ supply or 3.3V $\pm 10\%$ supply and is guaranteed over the full industrial temperature range (-40°C to $+85^{\circ}\text{C}$). For applications that require LVPECL outputs, consider the SY58021U or SY58022U 1:4 fanout buffer with 800 mV and 400 mV output swing, respectively. The SY58020U is part of Microchip's high-speed, Precision Edge[®] product line.

Package Type

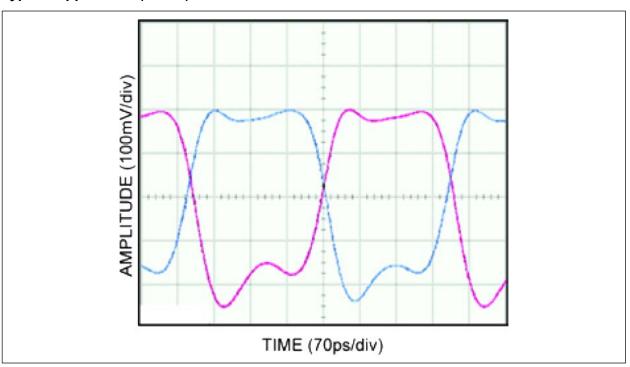


SY58020U

Functional Block Diagram



Typical Application (2 GHz)



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings[†]

Power Supply Voltage (V _{CC})	
Input Voltage (V _{IN})	–0.5V to V _{CC}
CML Output Voltage (V _{OLIT})	
Current (V _T), Source or sink current on V _T pin	
Input Current (I _{IN}), Source or sink current on IN, /IN	
Current (V _{RFF}), Source or sink current on V _{RFF-AC} (Note 1)	
TEL 70 ()	

Operating Ratings^{††}

Supply Voltage (V_{CC})+2.375V to +3.60V

Note 1: Due to the limited drive capability, use for input of the same package only.

TABLE 1-1: DC ELECTRICAL CHARACTERISTICS

All values applicable for when T _A = -40°C to +85°C unless otherwise noted. (Note 1)									
Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions			
Dower Supply Voltage	W	2.375	2.500	2.625	V	V _{CC} = 2.5V			
Power Supply Voltage	V _{CC}	3.000	3.300	3.600	V	V _{CC} = 3.3V			
Power Supply Current	I _{CC}	_	150	180	mA	No load, VCC = max. (include internal 50Ω pull-up)			
Input HIGH Voltage	V _{IH}	V _{CC} – 1.600	_	V _{CC}	V	Note 2			
Input LOW Voltage	V _{IL}	0	_	V _{IH} – 0.100	V	_			
Input Voltage Swing	V _{IN}	0.100	_	1.700	V	See Figure 7-1			
Differential Input Voltage Swing	V_{DIFF_IN}	0.200	_	3.400	V	See Figure 7-2			
IN-to-V _T Resistance	R _{IN}	40	50	60	Ω	_			
Output Reference Voltage	V _{REF-AC}	V _{CC} – 1.300	V _{CC} – 1.200	V _{CC} – 1.100	V	_			
IN-to-V _T Voltage	$V_{T_{IN}}$	_	_	1.280		_			

Note 1: The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

[†] **Notice:** Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

^{††} Notice: The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.

^{2:} V_{IH} (min.) not lower than 1.2V.

TABLE 1-2: CML DC ELECTRICAL CHARACTERISTICS

V_{CC} = 3.3V ±10% or 2.5V ±5%; R_L = 100 Ω ; and T_A = -40°C to +85°C, unless otherwise noted. (Note 1)									
Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions			
Output High Voltage	V _{OH}	V _{CC} – 0.020	V _{CC} – 0.020	V _{CC}	V	_			
Output Voltage Swing	V _{OUT}	325	400	500	mV	_			
Differential Output Voltage Swing	V _{DIFF_OUT}	650	800	1000	mV	_			
Output Source Impedance	R _{OUT}	40	50	60	Ω	_			

Note 1: The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

TABLE 1-3: AC ELECTRICAL CHARACTERISTICS

V_{CC} = 2.5V ±5% and T_A = -40°C to + 85°C, unless otherwise noted.									
Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions			
Maximum Operating Fraguency	f	6	_	_	GHz	V _{OUT} ≥ 200 mV (Clock)			
Maximum Operating Frequency	f _{MAX}	_	10	_	Gbps	NRZ Data			
Propagation Delay	t _{pd}	110	180	260	ps	_			
Output-to-Output Skew	4	_	4	15	ps	Note 1			
Part-to-Part Skew	t _{SKEW}	_	_	50	ps	Note 2			
Output Rise/Fall Time 20% to 80%	t _r , t _f	20	40	60	ps	At full swing			
Additive Phone litter		_	27	_	fsRMS	Carrier = 622 MHz, Integration Range: 12 kHz–20 MHz			
Additive Phase Jitter	t _{JITTER}	_	128	_	fsRMS	Carrier = 156.25 MHz, Integration Range: 12 kHz–20 MHz			

Note 1: Skew is measured between outputs under identical transitions.

TABLE 1-4: TEMPERATURE SPECIFICATIONS

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Temperature Range			1		1	
Operating Ambient Temperature	T _A	-40	_	+85	°C	_
Lead Temperature	T _{LEAD}	_	+260	_	°C	Soldering, 20 sec.
Storage Temperature	T _S	-65	_	+150	°C	_
Package Thermal Resistance						
VQFN, Still Air		_	+60	_	°C/W	_
VQFN, 500 Ifpm	θ_{JA}	_	+54	_	°C/W	_
VQFN, Junction-to-Board (Note 1)	ΨJB	_	+33	_	°C/W	_

Note 1: Thermal performance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB.

^{2:} Skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1, 4	IN, /IN	Differential Input: This input pair receives the signal to be buffered. Each pin of this pair internally terminates with 50Ω to the VT pin. Note that this input will default to an indeterminate state if left open. See "Input Interface Applications" section.
2	VT	Input Termination Center-Tap: Each input terminates to this pin. The VT pin provides a center-tap for each input (IN, /IN) to the termination network for maximum interface flexibility. See "Input Interface Applications" section.
3	VREF-AC	Reference Output Voltage: This output biases to V_{CC} – 1.2V. It is used when AC-coupling to differential inputs. Connect VREF-AC directly to the VT pin. Bypass with 0.01 μ F low ESR capacitor to VCC. See "Input Interface Applications" section.
8, 13	VCC	Positive Power Supply: Bypass with 0.1 μ F 0.01 μ F low ESR capacitors as close to the pins as possible.
5, 16	GND, Exposed Pad	Ground. Exposed pad must be connected to a ground plane that is the same potential as the ground pin.
14, 15 11, 12 9, 10 6, 7	/Q0, Q0 /Q1. Q1 /Q2. Q2 /Q3. Q3	CML Differential Output Pairs: Differential buffered output copy of the input signal. The output swing is typically 400 mV into 50Ω load. Normally terminate CML output pairs with 100Ω across Q and /Q outputs at the receiving end. Unused output pairs may be left floating with no impact on jitter or skew. See "CML Output Termination" section.

3.0 TYPICAL CHARACTERISTICS

 V_{CC} = 2.5V; GND = 0; V_{IN} = 100 mV; and T_A = 25°C, unless otherwise noted.

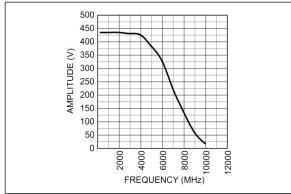


FIGURE 3-1: AMPLITUDE VS. FREQUENCY.

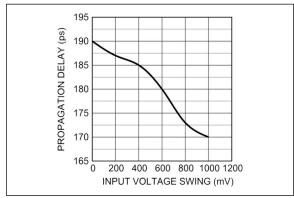


FIGURE 3-3: PROPAGATION DELAY VS. INPUT VOLTAGE SWING.

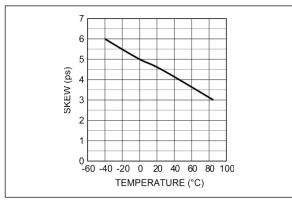


FIGURE 3-2: SKEW VS. TEMPERATURE.

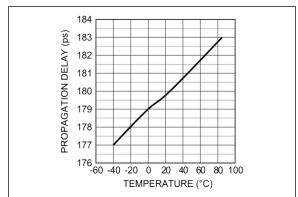


FIGURE 3-4: PROPAGATION DELAY VS. TEMPERATURE.

4.0 TYPICAL OUTPUT WAVEFORMS

 V_{CC} = 2.5V; GND = 0; V_{IN} = 100 mV; and T_A = 25°C, unless otherwise noted.

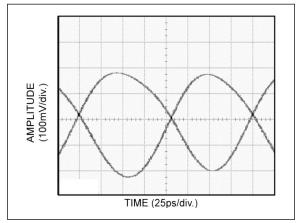


FIGURE 4-1: 5 GHZ OUTPUT.

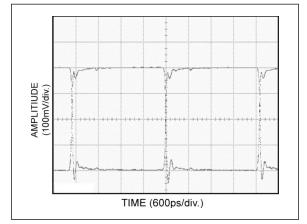


FIGURE 4-2: 200 MHZ OUTPUT.

5.0 ADDITIVE PHASE NOISE PLOTS

 V_{CC} = 3.3V; GND = 0; and T_A = 25°C, unless otherwise noted.

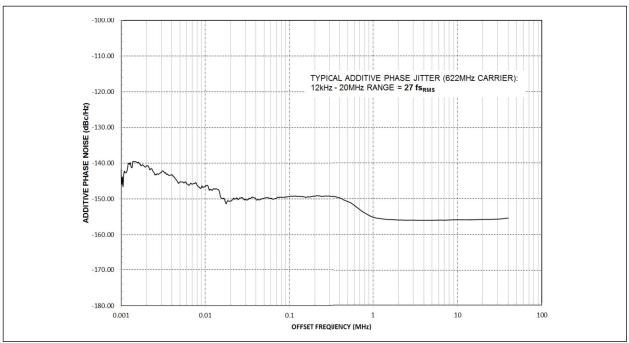


FIGURE 5-1: TYPICAL ADDITIVE PHASE JITTER (622 MHZ CARRIER), 12 KHZ–20 MHZ RANGE = 27 FS_{RMS}.

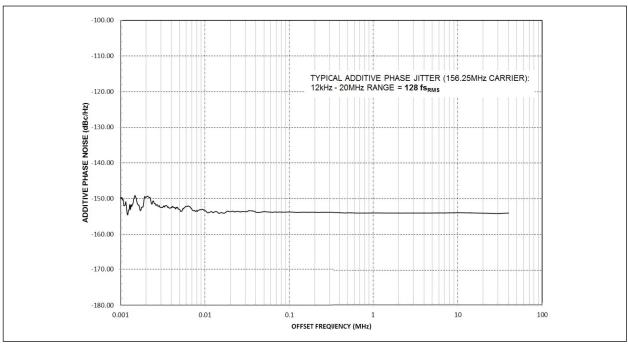


FIGURE 5-2: TYPICAL ADDITIVE PHASE JITTER (156.25 MHZ CARRIER), 12 KHZ-20 MHZ RANGE = 128 FS_{RMS}.

6.0 CML OUTPUT TERMINATION

Figure 6-1 and Figure 6-2 illustrate a CML output using both the AC-coupled and DC-coupled configuration. All outputs of the SY58020U are 50Ω with a 16 mA current source.

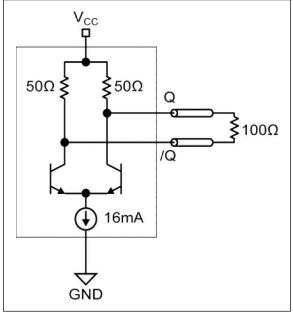


FIGURE 6-1: CML DC-COUPLED OUTPUT.

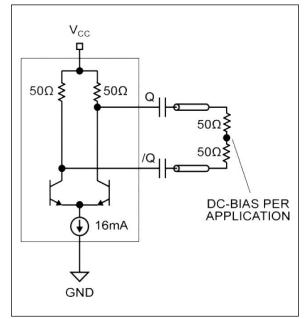


FIGURE 6-2: CML AC-COUPLED TERMINATION.

7.0 SINGLE-ENDED AND DIFFERENTIAL SWINGS

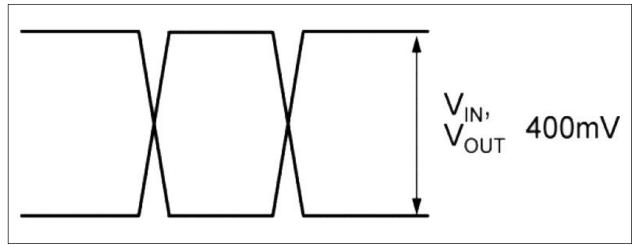


FIGURE 7-1: SINGLE-ENDED VOLTAGE SWING.

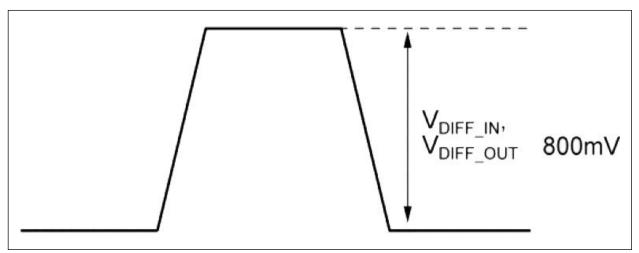


FIGURE 7-2: DIFFERENTIAL VOLTAGE SWING.

8.0 TIMING DIAGRAM

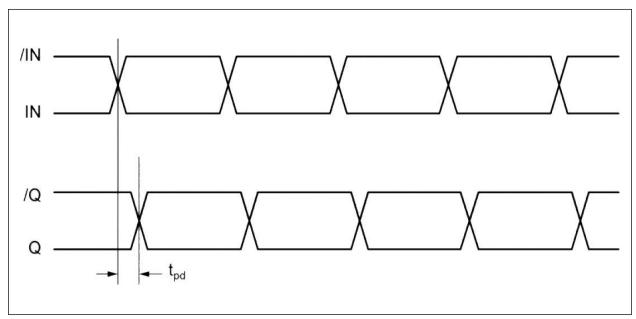


FIGURE 8-1: TIMING DIAGRAM.

9.0 INPUT STAGE

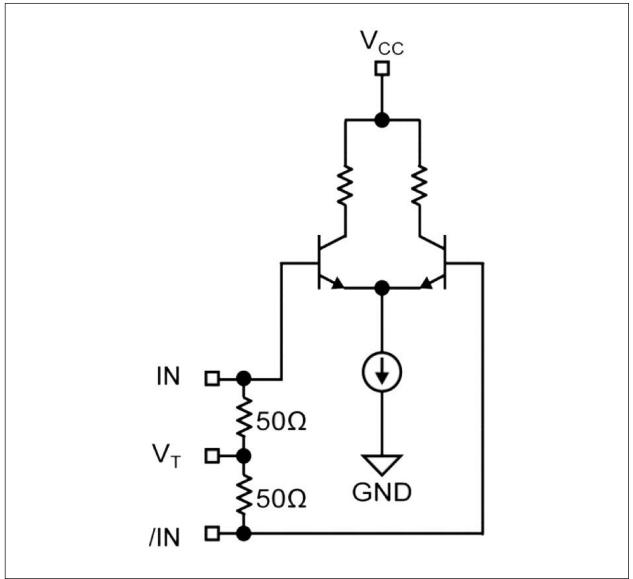


FIGURE 9-1: SIMPLIFIED DIFFERENTIAL INPUT BUFFER.

10.0 INPUT INTERFACE APPLICATIONS

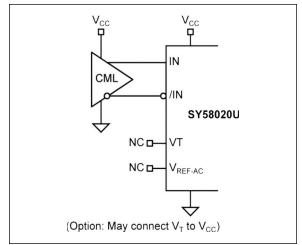


FIGURE 10-1: DC-COUPLED CML INPUT INTERFACE.

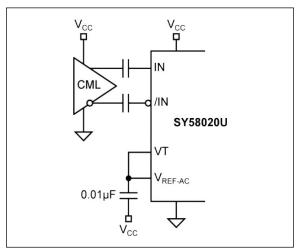


FIGURE 10-2: AC-COUPLED CML INPUT INTERFACE.

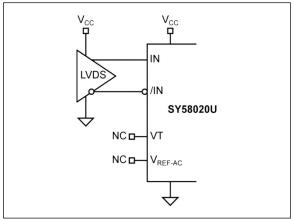


FIGURE 10-3: DC-COUPLED LVDS INPUT INTERFACE.

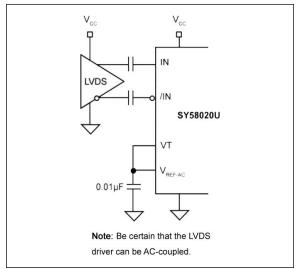


FIGURE 10-4: AC-COUPLED LVDS INPUT INTERFACE.

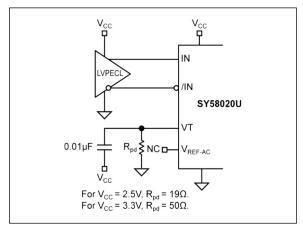


FIGURE 10-5: DC-COUPLED LVPECL INPUT INTERFACE.

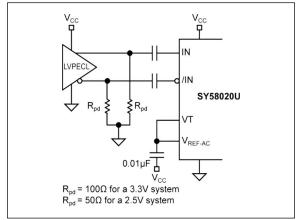
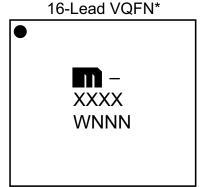


FIGURE 10-6: AC-COUPLED LVPECL INPUT INTERFACE.

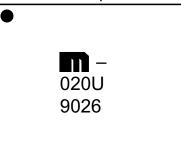
11.0 PACKAGING INFORMATION

11.1 Package Marking Information





Example*



Legend: XX...X Product code or customer-specific information

W Week code

NNN Alphanumeric traceability code (week)

* This package is Pb-free. The Pb-free JEDEC designator can be found on the outer packaging for this package.

Pin one index is identified by a dot

Note: In the event the full Microchip part number cannot be marked on one line, it will

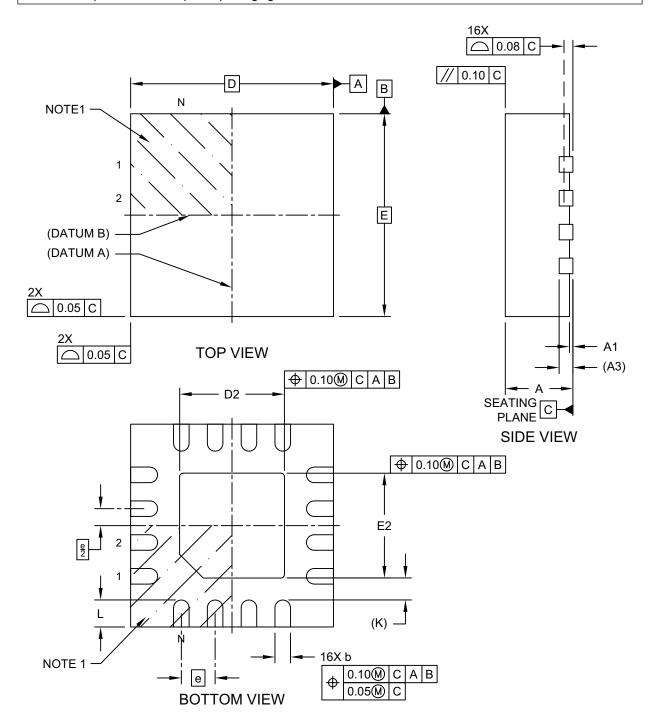
be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include

the corporate logo.

Underbar (_) and/or Overbar (_) symbol may not be to scale.

16-Lead 3 mm × 3 mm VQFN [NCA] Package Outline and Recommended Land Pattern

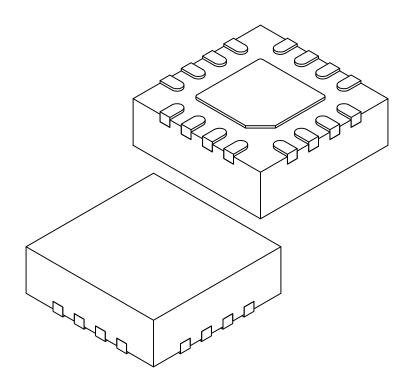
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1103-NCA Rev C Sheet 1 of 2

16-Lead 3 mm × 3 mm VQFN [NCA] Package Outline and Recommended Land Pattern

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS				
Dimension	Limits	MIN	NOM	MAX	
Number of Terminals	N		16		
Pitch	е		0.50 BSC		
Overall Height	Α	0.80	0.90	1.00	
Standoff	A1	0.00 0.02 0.0			
Terminal Thickness	A3	0.203 REF			
Overall Length	D		3.00 BSC		
Exposed Pad Length	D2	1.50	1.55	1.60	
Overall Width	Е		3.00 BSC		
Exposed Pad Width	E2	1.50	1.55	1.60	
Terminal Width	b	0.18 0.23 0.2			
Terminal Length	L	0.35	0.40	0.45	
Terminal-to-Exposed-Pad	K		0.33 REF		

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M

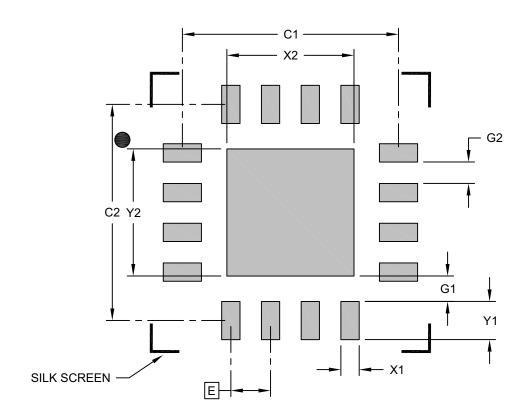
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1103-NCA Rev C Sheet 2 of 2

16-Lead 3 mm × 3 mm VQFN [NCA] Package Outline and Recommended Land Pattern

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units				
Dimension	Dimension Limits			MAX	
Contact Pitch	Е		0.50 BSC		
Center Pad Width	X2			1.60	
Center Pad Length	Y2			1.60	
Contact Pad Spacing	C1		2.72		
Contact Pad Spacing	C2		2.72		
Contact Pad Width (Xnn)	X1			0.23	
Contact Pad Length (Xnn)	Y1			0.48	
Contact Pad to Center Pad (Xnn)	G1	0.32			
Contact Pad to Contact Pad (Xnn)	G2	0.27			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-3103-NCA Rev C

61		0	Λ	2	A		
J I	I J	O	U	Z	U	L	J

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (February 2024)

- Converted Micrel data sheet for SY58020U to Microchip format as DS20006872A.
- Minor text changes throughout.

61		0	Λ	2	A		
J I	I J	O	U	Z	U	L	J

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	X	X	<u> </u>
Device	Supply P Voltage Range	acka	ge Temperature Special Range Processing
Device:	SY58020	=	6 GHz, 1:4 CML Fanout Buffer/ Translator with Internal I/O Termination
Voltage Option:	U	=	2.5V/3.3V
Package:	М	=	16-Lead VQFN
Temperature Range:	G	=	–40°C to 85°C
Special Processing:	<blaue></blaue>	= =	100/Tube 1,000/Reel

Examples:

a) SY58020UMG

 $2.5 \text{V}/3.3 \text{V},~16\text{-Lead}~\text{VQFN},~-40^{\circ}\text{C}~\text{to}~85^{\circ}\text{C},~100/\text{Tube}$

b) SY58020UMG-TR

2.5V/3.3V, 16-Lead VQFN, -40° C to 85°C, 1,000/Reel

61	1 5	0	$\mathbf{\Omega}$	7	A		
J I	I J	O	U	Z	U	L	J

NOTES:

Note the following details of the code protection feature on Microchip products:

- · Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
- Microchip values and aggressively protects its intellectual property rights. Attempts to breach the code protection features of Microchip product is strictly prohibited and may violate the Digital Millennium Copyright Act.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not
 mean that we are guaranteeing the product is "unbreakable" Code protection is constantly evolving. Microchip is committed to
 continuously improving the code protection features of our products.

This publication and the information herein may be used only with Microchip products, including to design, test, and integrate Microchip products with your application. Use of this information in any other manner violates these terms. Information regarding device applications is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. Contact your local Microchip sales office for additional support or, obtain additional support at https://www.microchip.com/en-us/support/design-help/client-support-services.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE, OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDIRECT, SPECIAL, PUNITIVE, INCIDENTAL, OR CONSEQUENTIAL LOSS, DAMAGE, COST, OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION.

Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

Trademarks

The Microchip name and logo, the Microchip logo, Adaptec, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, CryptoMemory, CryptoRF, dsPlC, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, ClockWorks, The Embedded Control Solutions Company, EtherSynch, Flashtec, Hyper Speed Control, HyperLight Load, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, TimeCesium, TimeHub, TimePictra, TimeProvider, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, Clockstudio, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, EyeOpen, GridTime, IdealBridge, IGaT, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, IntelliMOS, Inter-Chip Connectivity, JitterBlocker, Knob-on-Display, MarginLink, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mSiC, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, Power MOS IV, Power MOS 7, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SmartHLS, SMART-I.S., storClad, SQI, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, Trusted Time, TSHARC, Turing, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2024, Microchip Technology Incorporated and its subsidiaries.

All Rights Reserved.

ISBN: 978-1-6683-4077-6

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.



Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199

Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://www.microchip.com/ support

Web Address:

www.microchip.com

Atlanta Duluth, GA

Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Novi, MI

Tel: 248-848-4000

Houston, TX Tel: 281-894-5983

Tel: 281-894-598 Indianapolis

Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

San Jose, CA Tel: 408-735-9110 Tel: 408-436-4270

Canada - Toronto Tel: 905-695-1980 Fax: 905-695-2078

ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733

China - Beijing Tel: 86-10-8569-7000

China - Chengdu Tel: 86-28-8665-5511

China - Chongqing Tel: 86-23-8980-9588

China - Dongguan Tel: 86-769-8702-9880

China - Guangzhou Tel: 86-20-8755-8029

China - Hangzhou Tel: 86-571-8792-8115

China - Hong Kong SAR Tel: 852-2943-5100

China - Nanjing Tel: 86-25-8473-2460

China - Qingdao Tel: 86-532-8502-7355

China - Shanghai Tel: 86-21-3326-8000

China - Shenyang Tel: 86-24-2334-2829

China - Shenzhen Tel: 86-755-8864-2200

China - Suzhou Tel: 86-186-6233-1526

China - Wuhan

Tel: 86-27-5980-5300 China - Xian

Tel: 86-29-8833-7252

China - Xiamen Tel: 86-592-2388138

China - Zhuhai Tel: 86-756-3210040

ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444

India - New Delhi Tel: 91-11-4160-8631

India - Pune Tel: 91-20-4121-0141

Japan - Osaka Tel: 81-6-6152-7160

Japan - Tokyo

Tel: 81-3-6880- 3770

Korea - Daegu Tel: 82-53-744-4301

Korea - Seoul Tel: 82-2-554-7200

Malaysia - Kuala Lumpur Tel: 60-3-7651-7906

Malaysia - Penang Tel: 60-4-227-8870

Philippines - Manila Tel: 63-2-634-9065

Singapore Tel: 65-6334-8870

Taiwan - Hsin Chu Tel: 886-3-577-8366

Taiwan - Kaohsiung Tel: 886-7-213-7830

Taiwan - Taipei Tel: 886-2-2508-8600

Thailand - Bangkok Tel: 66-2-694-1351

Vietnam - Ho Chi Minh Tel: 84-28-5448-2100

EUROPE

Austria - Wels Tel: 43-7242-2244-39

Fax: 43-7242-2244-393

Denmark - Copenhagen Tel: 45-4485-5910 Fax: 45-4485-2829

Finland - Espoo Tel: 358-9-4520-820

France - Paris
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Garching Tel: 49-8931-9700

Germany - Haan Tel: 49-2129-3766400

Germany - Heilbronn Tel: 49-7131-72400

Germany - Karlsruhe Tel: 49-721-625370

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Germany - Rosenheim Tel: 49-8031-354-560

Israel - Ra'anana Tel: 972-9-744-7705

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Padova Tel: 39-049-7625286

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Norway - Trondheim Tel: 47-7288-4388

Poland - Warsaw Tel: 48-22-3325737

Romania - Bucharest Tel: 40-21-407-87-50

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Gothenberg Tel: 46-31-704-60-40

Sweden - Stockholm Tel: 46-8-5090-4654

UK - Wokingham Tel: 44-118-921-5800 Fax: 44-118-921-5820